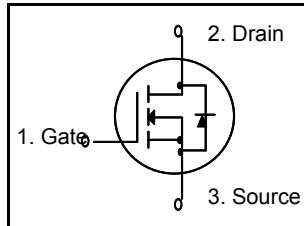


N-Channel MOSFET

Features

- High ruggedness
- $R_{DS(on)}$ (Max 5.5 Ω) @ $V_{GS} = 10V$
- Gate Charge (Typical 15nC)
- Improved dv/dt Capability
- 100% Avalanche Tested

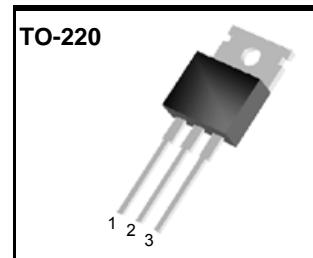


$BV_{DSS} = 600V$
 $R_{DS(ON)} = 5.5 \text{ ohm}$
 $I_D = 2.4A$

General Description

This N-channel enhancement mode field-effect power transistor using DI semiconductor's advanced planar stripe, DMOS technology intended for off-line switch mode power supply.

Also, especially designed to minimize $r_{ds(on)}$ and high rugged avalanche characteristics. The TO-220F PAK pkg is well suited for charger SMPS and small power inverter application.



Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V_{DSS}	Drain to Source Voltage	600	V
I_D	Continuous Drain Current(@ $T_C = 25^\circ\text{C}$)	2.4	A
	Continuous Drain Current(@ $T_C = 100^\circ\text{C}$)	1.5	A
I_{DM}	Drain Current Pulsed	(Note 1)	A
V_{GS}	Gate to Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy	(Note 2)	mJ
E_{AR}	Repetitive Avalanche Energy	(Note 1)	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	V/ns
P_D	Total Power Dissipation(@ $T_C = 25^\circ\text{C}$)	64	W
	Derating Factor above 25 °C	0.50	W/°C
T_{STG}, T_J	Operating Junction Temperature & Storage Temperature	-55 ~ 150	°C
T_L	Maximum Lead Temperature for soldering purpose, 1/8 from Case for 5 seconds.	300	°C

Thermal Characteristics

Symbol	Parameter	Value			Units
		Min.	Typ.	Max.	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	-	-	1.95	°C/W
$R_{\theta CS}$	Thermal Resistance, Case to Sink	0.5	-	-	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	-	-	62.5	°C/W

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Electrical Characteristics ($T_C = 25^\circ C$ unless otherwise noted)

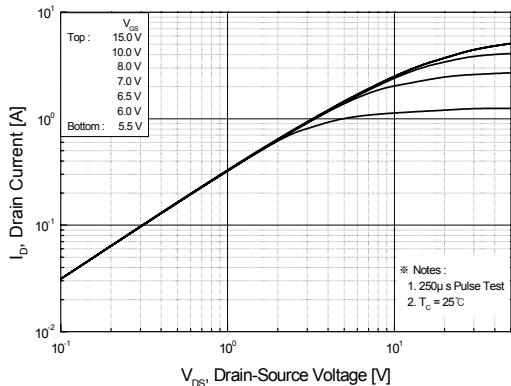
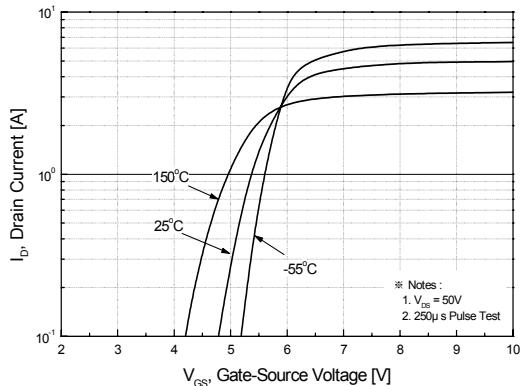
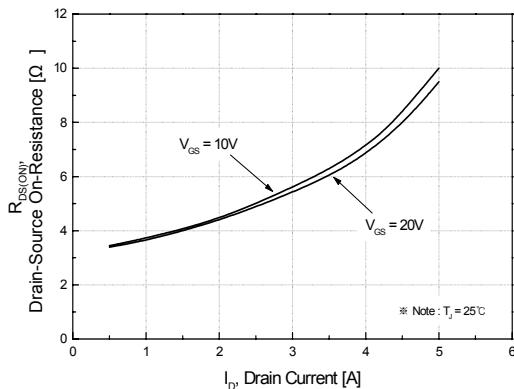
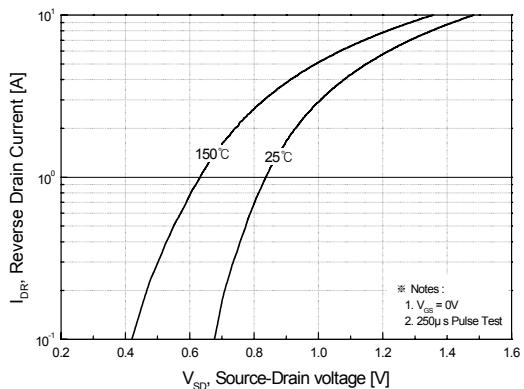
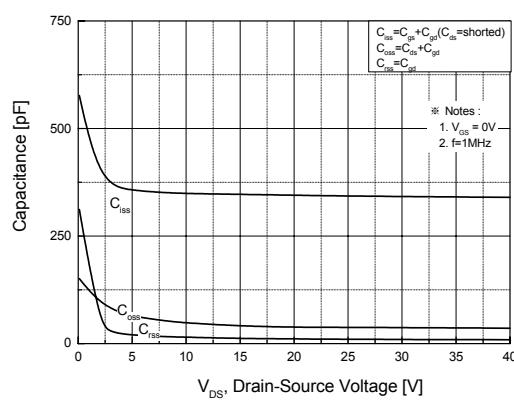
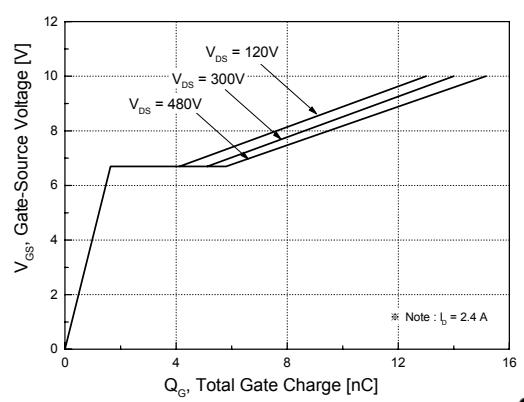
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	600	-	-	V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature coefficient	$I_D = 250\mu A$, referenced to $25^\circ C$	-	0.4	-	V/ $^\circ C$
I_{DSS}	Drain-Source Leakage Current	$V_{DS} = 600V, V_{GS} = 0V$	-	-	10	μA
		$V_{DS} = 480V, T_C = 125^\circ C$	-	-	100	μA
I_{GSS}	Gate-Source Leakage, Forward	$V_{GS} = 30V, V_{DS} = 0V$	-	-	100	nA
	Gate-source Leakage, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	-	-	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.0	-	4.0	V
$R_{DS(ON)}$	Static Drain-Source On-state Resistance	$V_{GS} = 10V, I_D = 1.0A$	-	4.5	5.5	Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$	-	570	720	pF
C_{oss}	Output Capacitance		-	150	215	
C_{rss}	Reverse Transfer Capacitance		-	310	450	
Dynamic Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 300V, I_D = 2.4A, R_G = 25\Omega$ * see fig. 13. (Note 4, 5)	-	15	35	ns
t_r	Rise Time		-	75	140	
$t_{d(off)}$	Turn-off Delay Time		-	30	60	
t_f	Fall Time		-	35	60	
Q_g	Total Gate Charge	$V_{DS} = 480V, V_{GS} = 10V, I_D = 2.4A$ * see fig. 12. (Note 4, 5)	-	15	20	nC
Q_{gs}	Gate-Source Charge		-	1.6	-	
Q_{gd}	Gate-Drain Charge(Miller Charge)		-	6	-	

Source-Drain Diode Ratings and Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit.
I_S	Continuous Source Current	Integral Reverse p-n Junction Diode in the MOSFET	-	-	2.0	A
I_{SM}	Pulsed Source Current		-	-	8.0	
V_{SD}	Diode Forward Voltage	$I_S = 2.4A, V_{GS} = 0V$	-	-	1.4	V
t_{rr}	Reverse Recovery Time	$I_S = 2.4A, V_{GS} = 0V, dI_F/dt = 100A/us$	-	820	-	ns
Q_{rr}	Reverse Recovery Charge		-	0.82	-	uC

* NOTES

1. Repetitive rating : pulse width limited by junction temperature
2. $L = 47mH, I_{AS} = 2.4A, V_{DD} = 50V, R_G = 50\Omega$, Starting $T_J = 25^\circ C$
3. $I_{SD} \leq 2.4A, di/dt \leq 300A/us, V_{DD} \leq BV_{DSS}$. Starting $T_J = 25^\circ C$
4. Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$
5. Essentially independent of operating temperature.

DFP2N60**Fig 1. On-State Characteristics****Fig 2. Transfer Characteristics****Fig 3. On Resistance Variation vs. Drain Current and Gate Voltage****Fig 4. On State Current vs. Allowable Case Temperature****Fig 5. Capacitance Characteristics (Non-Repetitive)****Fig 6. Gate Charge Characteristics**

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Fig 7. Breakdown Voltage Variation vs. Junction Temperature

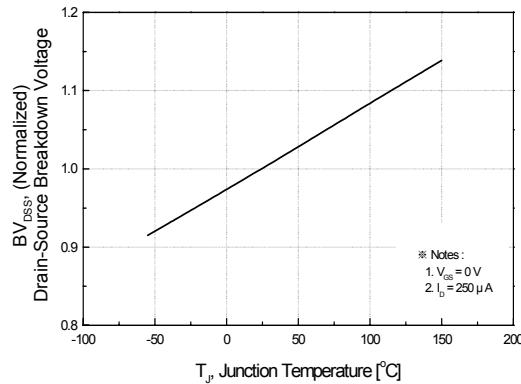


Fig 9. Maximum Safe Operating Area

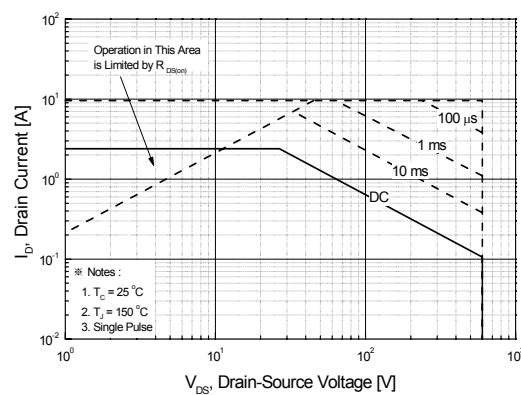


Fig 8. On-Resistance Variation vs. Junction Temperature

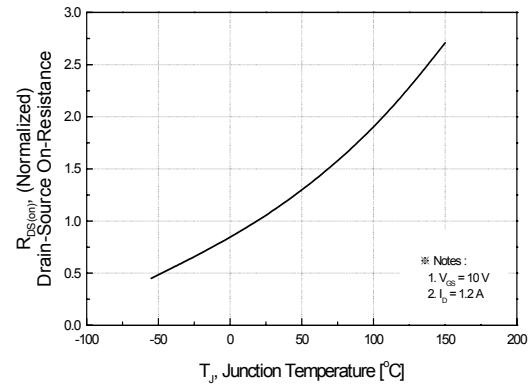


Fig 10. Maximum Drain Current vs. Case Temperature

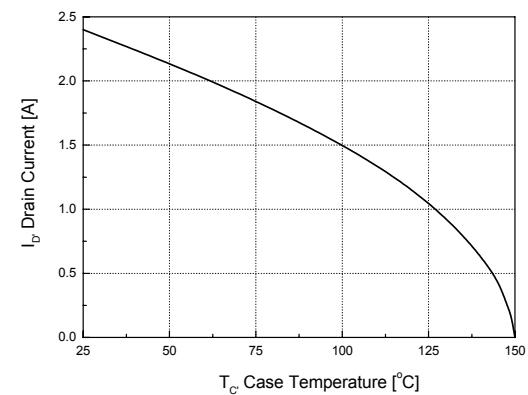
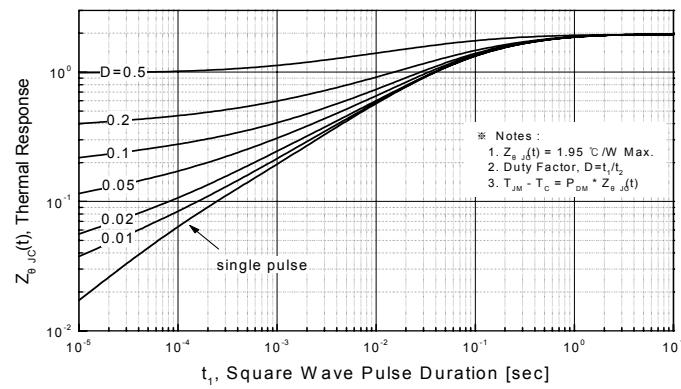


Fig 11. Transient Thermal Response Curve



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Fig. 12. Gate Charge Test Circuit & Waveforms

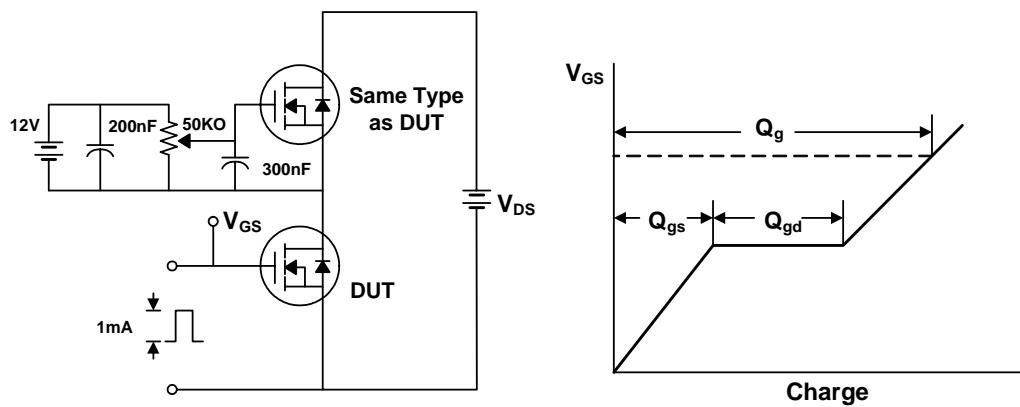


Fig 13. Switching Time Test Circuit & Waveforms

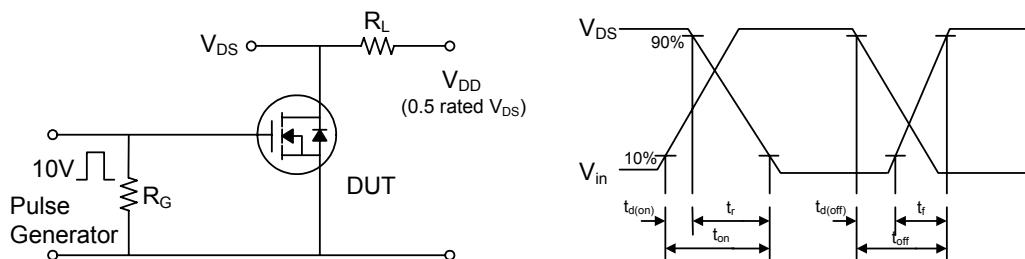
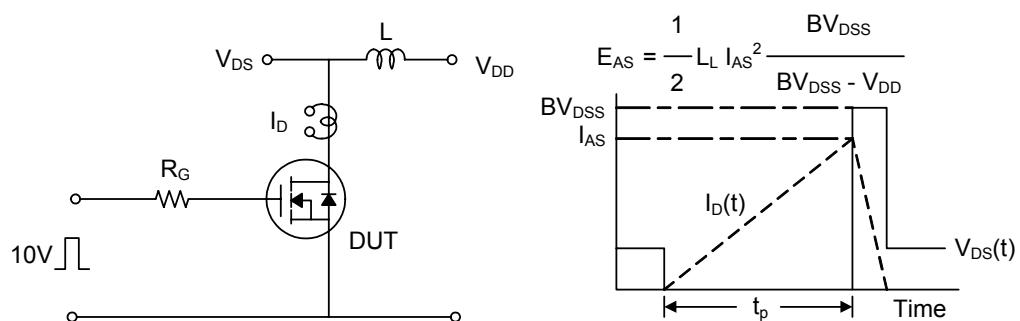
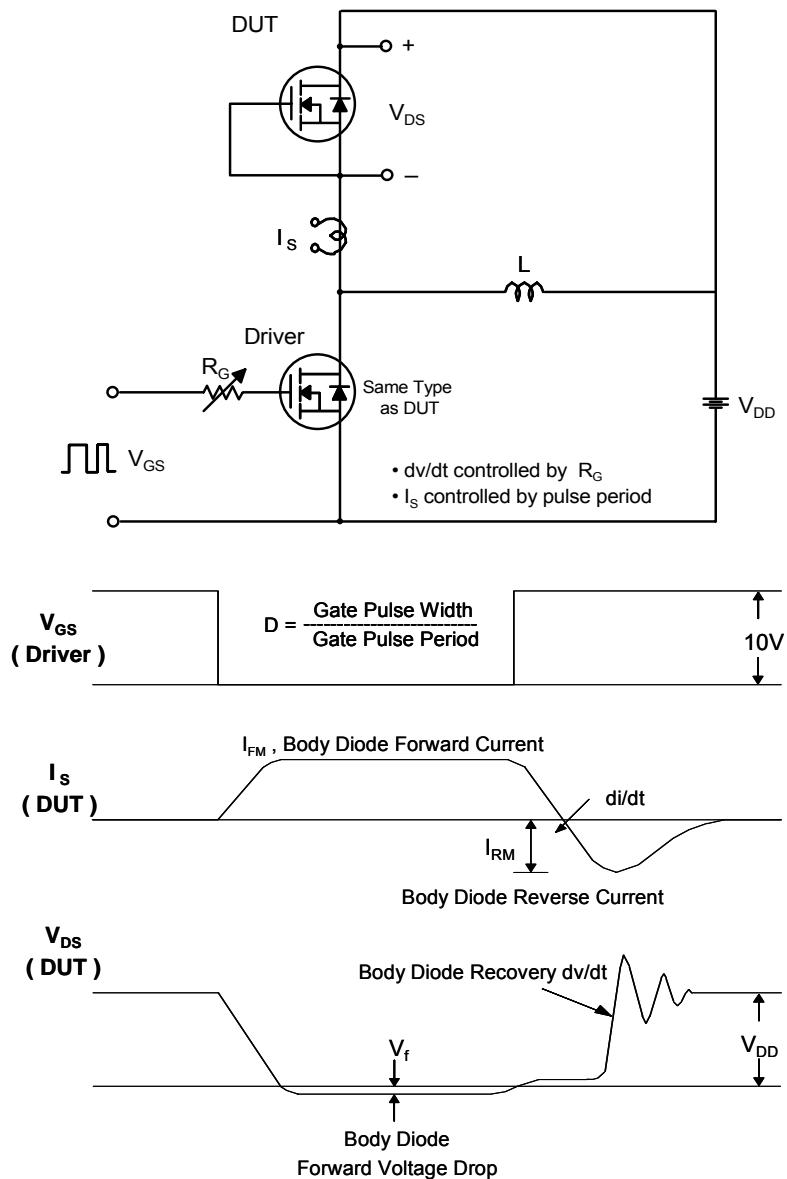


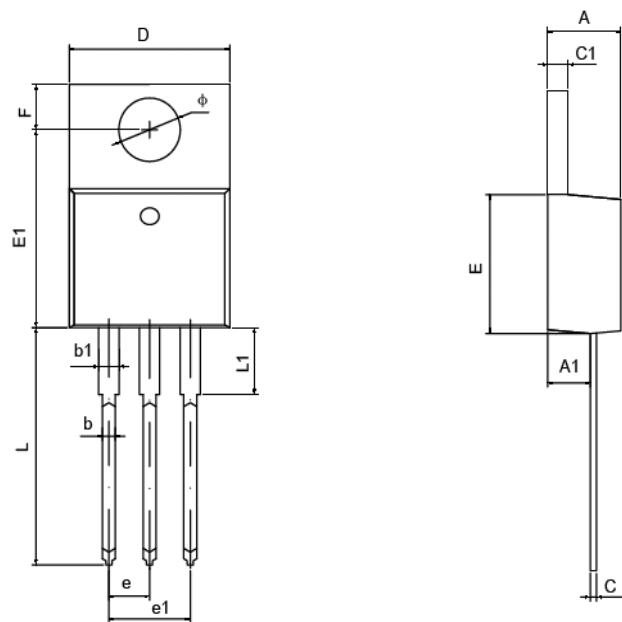
Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



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Fig. 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



DFP2N60**TO-220 Package Dimension**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	4.420	4.720	1.174	0.186
A1	2.520	2.820	0.099	0.111
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.360	0.460	0.014	0.018
c1	1.170	1.370	0.046	0.054
D	9.950	10.250	0.392	0.404
E	8.990	9.290	0.354	0.366
E1	12.550	12.850	0.494	0.506
e	2.540TYP		0.100TYP	
e1	4.980	5.180	0.196	0.204
F	2.590	2.890	0.102	0.114
L	13.080	13.480	0.515	0.531
L1	2.470	2.870	0.097	0.113
φ	3.790	3.890	0.149	0.153